

ABSTRACT

The present invention provides a conductive connecting material having a multilayered structure comprising a resin composition (A) and a metal foil (B) selected
5 from a solder foil or a tin foil, wherein the volume ratio ((A)/(B)) of the resin composition (A) and the metal foil (B) selected from a solder foil or a tin foil in the conductive connecting material is 1-40 or 20-500, as well as a method for connecting terminals using the conductive connecting material. The conductive connecting material of the present invention is preferably used for electrically connecting electronic members in an electrical
10 or electronic component.